PROTAVIC KOREA

TECHNICAL DATA SHEET

PVIC[®] ACE24511

Formerly TC-A(R1)

ELECTRICALLY CONDUCTIVE FAST CURE DIE ATTACH ADHESIVE

Description

PVIC® ACE24511 electrically conductive die attach adhesive is specially designed for tantalum condenser application. This single component, fast cure adhesive also can be snap cured in hot plate or in-line snap cure system and its excellent electrical conductivity and flexibility are considered as the strength for this material. In addition, it has improved dispensability than PVIC[®] ACE24510.

Application Package

CHIP TANTALUM CONDENSOR

Features

Single component Low volume resistivity Low stress Fast cure (also can be Snap cured in hot plate or in-line snap cure oven)

Filler type	Silver
Resin	Ероху
Cure Condition	At 160°C for 10 min (alternate cure condition in box oven)
Work life @ 22°C	24 hours
Estimated Storage life at -40°C	1 year

Properties

TEST ITEMS Viscosity @ 25°C	STANDARD 18180cps @ 5.0 rpm	TEST METHOD BHS-K-108
Thixotropic Index	5.54	BHS-K-108
Volume Resistivity	0.000155 ohm-cm	BHS-K-110
Die Shear Strength (Si to Cu L/F) @ RT (58×50mil ²)	4.50 kg	BHS-K-109
DSC	Onset 144.40°C Peak 158.80°C	BHS-K-113
Weight loss on cure	6.20 Wt.%	BHS-K-111
Glass Transition Temp. (Tg)	52 °C	BHS-K-116

Instruction

Thawing

Place the container to stand vertically for $30\min - 1$ hour. **DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40 or colder. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

PVIC adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.

The figures shown above are typical values only. If you need to generate a specification, please request our Standard Release Specification.